

ABSTRACT OF THE DISCLOSURE

In a wafer having an LD structure 251 formed on a GaN-based substrate 250, cleavage guide grooves 252 are formed in its surface by scribing from above the LD structure 251 with a diamond needle. The cleavage guide grooves 252 are formed one along each of stripe-shaped waveguides 253 formed parallel to the $\langle 1-100 \rangle$ direction of the wafer, and are formed in the shape of broken lines in the $\langle 11-20 \rangle$ direction of the wafer.